



LIST OF RELATED CASES

<u>Docket Number</u>	<u>Serial or Patent No.</u>	<u>Filing or Issue Date</u>	<u>Status or Patentee</u>
MB-213700US2-RD	09/947,355	09/07/01	PENDING
MB-215231US2-RD*	09/981,987	10/19/01	PENDING
MB-219138US2-SRD	10/060,247	02/01/02	PENDING
MB-224536US2-TTCRD	10/175,960	06/21/02	PENDING
MB-224586US2-TTCRD	10/178,023	06/24/02	PENDING
MB-226953US6 RD	10/217,410	08/14/02	PENDING

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*Present application; listed for information

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SHEET 1 OF 1

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U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

LIST OF REFERENCES CITED BY APPLICANT

ATTY DOCKET NO.	215231US2RD	SERIAL NO.
APPLICANT	Yuuzo KAMIGUCHI, et al.	
FILING DATE	October 19, 2001	GROUP

2651

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
AA	6,303,218	10/16/2001	Y. KAMIGUCHI, et al.			
AB						
AC						
AD						
AE						
AF						
AG						
AH						
AI						
AJ						
AK						
AL						
AM						
AN						

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FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES NO
AO				
AP				
AQ				
AR				
AS				
AT				
AU				
AV				

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)

MSB	AW	K. NAGASAKA, et al., The 8th Joint MMM-Intermag Conference, Abstracts, page 214, DD-10, "GIANT MAGNETORESISTANCE PROPERTIES OF SPECULAR SPIN VALVE FILMS IN CPP STRUCTURE", January 7-11, 2001
MSB	AX	K. NAGASAKA, et al., Journal of the Magnetic Society of Japan, vol. 25, no. 4-2, pages 807-810, "GIANT MAGNETORESISTANCE PROPERTIES OF SPIN VALVE FILMS IN CURRENT-PERPENDICULAR-TO-PLANE GEOMETRY", 2001 (with English Abstract)
	AY	
	AZ	

Examiner

Date Considered

11/17/03

*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.